Tool ID: 226
Tool Location: 102

Equipment Information Sheet

Xenon Difluoride SPTS

Manager: Ben Infante 607-254-4813
Backup: Jeremy Clark 607-254-6487
Backup: Philip Schneider 607-254-4931

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

System uses a vapor Fluorine source for etching - use caution during operation

High temperature chuck - use caution when loading/unloading samples

USAGE RESTRICTIONS

No buddy system restrictions

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 30 minutes

None

MATERIALS COMPATIBILITY CATEGORY

Tool Category 3: Silcion, III-V Compound Semiconductor, Glass and Metal Category

Allowed	Not Allowed
Tool category 1/1E and 2 materials	Glass Substrates
III/V compound Semiconductors allowed	No CNF Class A or Class B metals-and oxides/compounds of i.e. (Magnesium,Zinc, Barium, Calcium)
PECVD and ALD Films	No High Vapor pressure materials
Cured organics and baked Photoresist	
Organic/Bio Materials prepped w/o Salt Buffers	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Allowed samples include pieces and wafers up to 150 mm

Last Updated: 11/11/2026